

PATENT ABSTRACTS OF JAPAN

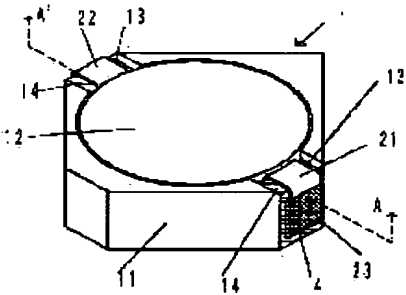
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(21)Application number : 08-190452 (71)Applicant : TDK CORP
(22)Date of filing : 19.07.1996 (72)Inventor : TAKAHASHI MINORU

(54) SURFACE MOUNTING TYPE COIL

(57)Abstract:
PROBLEM TO BE SOLVED: To improve mechanical strength and obtain reliability of an extension line by providing a through hole to a part wherein a lead terminal part is subjected to solder precoating.
SOLUTION: A through hole 23 is provided to a lead terminal part 21 of a circular line ring which is extended from an outer shell core structure body 1 comprised of a core case 11 and a lid 12 of a core to a groove part 13 of a core case and molded. (A through hole is similarly provided to a lead terminal part 22.) The lead terminal parts 21, 22 are fused to cover at least the through hole 23 by an electrode 14 of a core case and solder 4. Thereby, mechanical holding force of a lead terminal part is raised and reliability of an extension line is improved. Additionally, since solder after solder precoating enters a through hole, enough required amount of solder attaches and dispersion in fusing strength of a lead terminal of products can be restrained.



LEGAL STATUS

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